

## PRECAUTION FOR HANDLING

### 1. Soldering

- 1) Avoid the reflow method and solder to touch the body of the device during wave soldering. This is to prevent changes in optical characteristics of the device.
- 2) Recommended in Soldering

Temperature	Time Lead	Soldering Position
260 °C maximum	less than 10 seconds	At least 1.5mm from body
- 3) Soldering is recommended to be done in as short period of the time as possible by controlling the temperature of the soldering iron or by the iron of less than 15 watts.
- 4) The resin gets softened right after soldered, so, the following care has to be taken.
  - Not to contact the lens surface to anything
  - Not to dip the device into water or any solvents
- 5) It is recommended not to solder when the leads or between the lead get pulled, depressed or twisted.
- 6) In the case of using rosin flux, be careful to avoid contact with the lens surface. If the lens is covered with the flux, the specified characteristics cannot be achieved.

### 2. Post Solder Cleaning

- 1) Organic solvents for flux removal like trichloroethylene, acetone, thinner etc, might attach the lens surface. It is preferable to use less reactive solvents, Methyl Alcohol, Isopropyle Alcohol.
- 2) Cleaning Operation

Cleaning Solvent Temperature	: 35 °C maximum
Dipping Time	: 3 minute maximum

### 3. Attention in handling

- 1) Treat not to touch the lens surface.
- 2) Avoid dust and any other foreign materials (flux, paints, bonding material, etc.) on the lens surface.
- 3) When mounting, special care has to be taken on the mounting position and tilting of the device because it is very important to place the device to the optimum position to the object.

### 4. Storage

The leads are silver plated and they are discolored if the device is left open to the air for long after taken out of the envelop. It causes deterioration of soldering characteristics. Mount the device as short as possible after opening the envelope.

## MEMO

[CAUTION]

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